

Title (en)  
NICOCRALY-ALLOY, A POWDER, A COATING AND A COMPONENT

Title (de)  
NICOCRALY-LEGIERUNG, PULVER, BESCHICHTUNG UND KOMPONENTE

Title (fr)  
ALLIAGE DE NICOCRALY, POUDRE, REVÊTEMENT ET COMPOSANT

Publication  
**EP 3985137 A1 20220420 (EN)**

Application  
**EP 20201694 A 20201014**

Priority  
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Abstract (en)  
The invention comprises a Nickel-based alloy, and least comprising (in wt%): 25.7 % - 27.3% Cobalt (Co), 15.0% - 16.0% Chromium (Cr), 12.2% - 13.2% Aluminum (Al), 0.3% - 0.5% Yttrium (Y), 2.5% - 3.5% Ruthenium (Ru), 0.4% - 0.8% Silicon (Si), 0.4% - 0.6% Tantalum (Ta), 0.4% - 0.6% Molybdenum (Mo).

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Citation (applicant)

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